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Planning

Sub-Micron Die Bonder

UNIVERSITY OF SHEFFIELD

UK2: Preliminary market engagement notice - Procurement Act 2023 - [view information about notice types](#)

Notice identifier: 2025/S 000-081169

Procurement identifier (OCID): ocds-h6vhtk-05f213

Published 9 December 2025, 4:09pm

Scope

Reference

4915/DM/25

Description

We are seeking equipment that can provide a wide range of bonding technologies to cater for semiconductor die to wafer, die to chip, wafer to wafer, fli-chip and other semiconductor chiplet bonding, to support our work in Heterogeneous Integration for Microelectronics and Semiconductor Systems.

Total value (estimated)

- £380,000 including VAT

Above the relevant threshold

Contract dates (estimated)

- 2 March 2026 to 31 March 2026
- 30 days

Main procurement category

Goods

CPV classifications

- 38000000 - Laboratory, optical and precision equipments (excl. glasses)

Contract locations

- UKE32 - Sheffield

Engagement

Engagement deadline

26 November 2025

The engagement was carried out before this notice was published.

Engagement process description

Indicative quotations for budgetary purposes, were sought from two potential providers in November 2025, by one of the academic members of staff team at the University.

Participation

Particular suitability

- Small and medium-sized enterprises (SME)
- Voluntary, community and social enterprises (VCSE)

Submission

Publication date of tender notice (estimated)

16 December 2025

Contracting authority

UNIVERSITY OF SHEFFIELD

- Companies House: RC000667
- Public Procurement Organisation Number: PXDP-7327-GWHT

Firth Court, Western Bank

Sheffield

S10 2TN

United Kingdom

Email: procurement@sheffield.ac.uk

Website: <https://www.sheffield.ac.uk/>

Region: UKE32 - Sheffield

Organisation type: Public authority - sub-central government